

10042829

10042829

PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10042829	01/08/2002	228	41	1725	STONER, K

\*\*APPLICANTS: Cheng Chi; Chong Ping; Chan Chi; Chan Chin;

\*\*CONTINUING DATA VERIFIED:

\*\* FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		P/4076-10	
Verified and Acknowledged Examiners's initials <i>WJH KS</i>			
TITLE : Apparatus and method of placing solder balls onto a substrate			

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	Print Claim for O.G.
<b>ISSUE FEE</b>		<b>DRAWING</b>	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		Application Examiner	
		<b>PREPARED FOR ISSUE</b>	
<b>WARNING:</b> The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH: ☐ DISK (CRF) ☐ CD-ROM  
(Attached in pocket on right inside flap)